

# 75G5 3U cPCI Multifunction I/O Boards 3U cPCI Multifunction I/O Board

The 75G5 is NAI's rugged 3U cPCI multifunction I/O and communications board. It provides low power/high-performance I/O capabilities specifically designed for demanding aerospace, defense, and industrial applications. The board can accommodate up to three NAI Configurable Open Systems Architecture<sup>™</sup> (COSA®) smart function modules. By configuring the 75G5 with these modules, engineers can tailor the board's functionality for specific application needs, accelerating the deployment of SWaP-C optimized systems.



### **Features**

- Up to 3 independent smart I/O function modules supported
- Front and/or rear I/O
- Commercial or rugged applications
- < 5 W MB power dissipation</p>
- Independent x1 SerDes interface to each function module slot
- 2x 10/100/1000 Base-T Ethernet; 2 to rear or 1 to rear and 1 to front I/O
- Continuous Background Built-in-Test (BIT)
- Intelligent I/O library support included
- COSA® Architecture

- VICTORY Interface Services (Contact factory)
- Operating temp: 0° C to +70° C or Rugged -40° C to +85° C



## Select up to 3 independent functions for your application

I/O Modules										
Function	Module	Description		Function	Module	Description				
Analog-to-Digital	AD1	12 CH. A/D, ±10 V, Dedicated, 256 kHz (max), Sigma-Delta		Digital-to-Analog	DA5	4 CH. D/A, High-Voltage/High-Current Half-Bridge (2 Channels Full-Bridge) External VCC Sourced Outputs				
	AD2	12 CH. A/D, ±100 V (max), Dedicated, 256 kHz (max), Sigma-Delta			DF1	16 CH. Differential I/O, Input: -10 V to +10 V (422), -7 V to +12 V (485) Output:25 V to +5 V				
	AD3	12 CH. A/D, ±25 mA, Dedicated, 256 kHz (max), Sigma-Delta		Digital IO - Differential Transceiver	DF2	16 CH. 16 Channel Enhanced Differential I/O				
	AD4	16 CH. A/D, $\pm$ 10 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR			<u>DT1</u>	24 CH. Discrete I/O, 0-60 VDC Input/Output, Max lout 500 mA - 2 A, Source/Sink (out)				
	<u>AD5</u>	16 CH. A/D, $\pm$ 50 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR			<u>DT2</u>	16 CH. Discrete I/O, ±80 V Input/Output, Max lout 600 mA, Isolated/Ch Switch (out)				
	<u>AD6</u>	16 CH. A/D, $\pm$ 100 V, Multiplexed, 500 KHz Agg / 8 Ch, SAR		Discrete IO - Multichannel,Programmable	DT3	4 CH. Discrete Hi & Lo Side Switch Output @ 65V/2A (max), external individual supplied VCC & VSS per channel pair				
	<u>ADE</u>	16 CH. A/D, ±10 V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling			DT4	24 CH. Enhanced DT1				
	<u>ADF</u>	16 CH. A/D, $\pm 100$ V, Individual 16-bit SAR, 200 kHz max., Simultaneous Sampling			<u>DT5</u>	16 CH. Enhanced DT2				
Chip Detector and Fuzz Burn	<u>CD1</u>	6 CH. Chip Detector (CD) and Fuzz Burn (FB)		Relay	<u>RY1</u>	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Non Latching				
Digital-to-Analog	<u>DA1</u>	12 CH. D/A, $\pm$ 10 V, 25 mA Per Channel, Current or Voltage Control		кенау	<u>RY2</u>	4 CH. Relay, 220V/2A @ 60W/62.5VA (Max), Latching				
	<u>DA2</u>	16 CH. D/A, ± 10 V, 10 mA Per Channel, No Current Control		Digital IO - TTL,CMOS	<u>TL1</u>	24 CH. TTL I/O, Standard Functionality, Programmable				
	<u>DA3</u>	4 CH. D/A, ±40 V, ±100 mA, Voltage or Current Output			<u>TL2</u>	24 CH. TTL I/O, Enhanced Functionality, Programmable				
	<u>DA4</u>	4 CH. D/A, $\pm$ 20 to $\pm$ 80, 10 mA, Voltage Control Only		Variable Reluctance	<u>VR1</u>	8 CH. Variable Reluctance Signal Input and General-Purpose Pulse Counter, ±100 V, 100 kHz (max)				
Measurement & Simulation Modules										
Function	Module	Description		Function	Module	Description				
AC Reference	<u>AC2</u>	2 CH. AC Reference Source, 47 Hz - 20 KHz, $\pm$ 3% Acc, 2 – 28 Vrms, 6 VA (Max/Ch) Power		Synchro Resolver Measurement and	<u>DSx</u> (DRx)	1 - 3 CH. Digital to Synchro/Resolver, 2 - 90 VLL, 2 - 1115 Vrms Exc, 47 Hz - 20 kHz Freq				
	<u>AC3</u>	2 CH. AC Reference Source, 47 Hz - 2.5 KHz, ± 3% Acc, 28 – 115 Vrms, 6 VA (Max/Ch) Power		Simulation	<u>SDx</u>	4 CH. Synchro/Resolver to Digital, 2 - 90 Vrms Input, 2 - 115 Vrms Exc, 47 Hz to 20 kHz Freq				
LVDT RVDT Measurement and Simulation	<u>DLx</u>	1 - 3 CH. Digital to LVDT/RVDT, 2 - 90 Vrms Full Scale, 2 - 115 Vrms Exc, 47 Hz - 20 kHz Freq		IRIG Timecode Receiver and Generator	<u>RG1</u>	1 CH. IRIG Timing Function Interface				
	<u>LD1</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 47 Hz -1 KHz Freq			<u>RT1</u>	8 CH. Resistance Temperature Detectors (RTD), 2, 3, or 4 wire, 16 Bit Res, 16.7 Hz/Ch				
	LD2	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 1 KHz - 5 KHz Freq		Thermocouple and RTD Measurement	<u>TC1</u>	8 CH. Thermocouple, 4.17 - 470 Hz, ±100 mV A/D				
	<u>LD3</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 5 KHz - 10 KHz Freq			<u>TR1</u>	8 CH. Thermocouple (TCx) & Resistance Temperature Detectors (RTD), programmable per channel				
	<u>LD4</u>	4 CH. LVDT/RVDT to Digital, 2-28 Vrms Input, 2- 115 Vrms Exc, 10 KHz - 20 KHz Freq		Strain Gauge Measurement	<u>SG1</u>	4 CH. Strain Gauge, 4.7 Hz - 4.8 KHz, Measurement, Conventional 4-Arm Bridge				
	<u>LD5</u>	4 CH. LVDT/RVDT to Digital, 28-90 Vrms Input, 2- 115 Vrms Exc, 47 Hz - 1 KHz Freq								



Communication Modules										
Function	Module	Description		Function	Module	Description				
ARINC Communications	<u>AR1</u>	12 CH. ARINC 429, 100 KHz or 12.5 KHz, RX/TX, 256 Word Tx/Rx Buffer			<u>FTE</u>	2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled				
	<u>AR2</u>	1 CH. ARINC 568 (CH-1, RX & TX) & 1 Channel ARINC 579 (CH-2, Programmable RX or TX), 1024-Word TX & RX Buffers per Ch.		MIL-STD-1553B	<u>FTF</u>	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Direct Coupled				
CANBus Communications	<u>CB1</u>	8 CH. CANBus, CAN 2.0 A/B, 16 K RX/TX Buffer, 1 Mb/s Max Data Rate			<u>FTJ</u>	1 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled				
	<u>CB2</u>	8 CH. CANBus, J1939, 16 K RX/TX Buffer, 500 kb/s Max Data Rate		MIL-STD-1760	<u>FTK</u>	2 CH. MIL-STD-1760 (1553), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled				
	<u>CB3</u>	8 CH. CANBus, CAN 2.0 A/B (CB1) or J1939 (CB2) protocol layer programmable per channel		<u>s</u>	<u>SC1</u>	4 CH. Serial, RS-232/422/423 (MIL-STD-188C)/485, Non Isolated				
MIL-STD-1553B	<u>FTA</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Transformer Coupled 2 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled		Serial Communications	SC3	8 CH. (max) RS-232/422/485 Serial Communications or GPIO, Programmable, Non-isolated				
	<u>FTB</u>				SC5	4 CH. RS-232/422/485 communications, isolated per channel and from SYS GND				
	<u>FTC</u>	4 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM Per Channel, Transformer Coupled			<u>SC6</u>	4 CH. RS-232/422/485 communications, individual SYS GND provided per channel (non-isolated)				
	<u>FTD</u>	1 CH. MIL-STD-1553 (AMC), BC, RT, BM, BM/RT, 128 KB RAM, Direct Coupled								
Storage										
Function	Module	Description		Function	Module	Description				
SATA Solid State Drive (SSD)	<u>FM2</u>	1 CH. 480 GB MLC SATA Flash, extended temp -40°C to 85°C operation								
Combination Modules										
Function	Module	Description		Function	Module	Description				
Combo	<u>CM5</u>	2 CH. Dual-redundant MIL-STD-1553 & 8 Channel ARINC 429/575, 100 KHz or 12.5 KHz, RX or TX, 256 Word Tx/Rx Buffer		Combo	<u>CM8</u>	2 CH. Dual-redundant MIL-STD-1553 & 12 Channel Discrete I/O, 0-60 VDC Input/Output, Max lout 500 mA - 2 A, Source/Sink (out)				

### **Architected for Versatility**

NAI's Configurable Open Systems Architecture<sup>™</sup> (COSA®) offers a choice of over 100 smart I/O, communications, or Ethernet switch functions, providing the highest packaging density and greatest flexibility of ruggedized embedded product solutions in the industry. Preexisting, fully-tested functions can be combined in an unlimited number of ways quickly and easily.

#### **One-Source Efficiencies**

Eliminate man-months of integration with a configured, field-proven system from NAI. Specification to deployment is a seamless experience as all design, state-of-the-art manufacturing, assembly and test are performed - by one trusted source. All facilities are located within the U.S. and optimized for high-mix/low volume production runs and extended lifecycle support.

### **Product Lifecycle Management**

From design to production and beyond, NAI's product lifecycle management strategy ensures the long-term availability of COTS products through configuration management, technology refresh and obsolescence component purchase and storage.



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